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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	242000
Total RAM Bits	19822592
Number of I/O	384
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agtmd3g3f31i3n

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	68	%
		3.9	45	%
		3.95	28	%
		4	15	%
		4.05	13	%
		4.1	11	%
		4.15	9	%
		4.2	8	%
		4.25	7	%
		4.3	5.4	%
		4.35	3.2	%
		4.4	1.9	%
		4.45	1.1	%
		4.5	0.6	%
		4.55	0.4	%
		4.6	0.2	%

Recommended Operating Conditions

This section lists the functional operation limits for the AC and DC parameters for Arria V devices.

Recommended Operating Conditions

Table 1-3: Recommended Operating Conditions for Arria V Devices

This table lists the steady-state voltage values expected from Arria V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Transceiver Power Supply Operating Conditions

Table 1-4: Transceiver Power Supply Operating Conditions for Arria V Devices

Symbol	Description	Minimum ⁽⁵⁾	Typical	Maximum ⁽⁵⁾	Unit
V _{CCA_GXBL}	Transceiver high voltage power (left side)	2.375	2.500	2.625	V
V _{CCA_GXBR}	Transceiver high voltage power (right side)				
V _{CCR_GXBL}	GX and SX speed grades—receiver power (left side)	1.08/1.12	1.1/1.15 ⁽⁶⁾	1.14/1.18	V
V _{CCR_GXBR}	GX and SX speed grades—receiver power (right side)				
V _{CCR_GXBL}	GT and ST speed grades—receiver power (left side)	1.17	1.20	1.23	V
V _{CCR_GXBR}	GT and ST speed grades—receiver power (right side)				
V _{CCT_GXBL}	GX and SX speed grades—transmitter power (left side)	1.08/1.12	1.1/1.15 ⁽⁶⁾	1.14/1.18	V
V _{CCT_GXBR}	GX and SX speed grades—transmitter power (right side)				
V _{CCT_GXBL}	GT and ST speed grades—transmitter power (left side)	1.17	1.20	1.23	V
V _{CCT_GXBR}	GT and ST speed grades—transmitter power (right side)				
V _{CCH_GXBL}	Transmitter output buffer power (left side)	1.425	1.500	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power (right side)				

⁽⁵⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁶⁾ For data rate ≤ 3.2 Gbps, connect V_{CCR_GXBL/R}, V_{CCT_GXBL/R}, or V_{CCL_GXBL/R} to either 1.1-V or 1.15-V power supply. For data rate > 3.2 Gbps, connect V_{CCR_GXBL/R}, V_{CCT_GXBL/R}, or V_{CCL_GXBL/R} to a 1.15-V power supply. For details, refer to the Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines.

Symbol	Description	Condition (V)	Calibration Accuracy			Unit
			-I3, -C4	-I5, -C5	-C6	
60- Ω and 120- Ω R _T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	-10 to +40	%
25- Ω R _{S_left_shift}	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%

OCT Without Calibration Resistance Tolerance Specifications

Table 1-9: OCT Without Calibration Resistance Tolerance Specifications for Arria V Devices

This table lists the Arria V OCT without calibration resistance tolerance to PVT changes.

Symbol	Description	Condition (V)	ResistanceTolerance			Unit
			-I3, -C4	-I5, -C5	-C6	
25- Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 3.0, 2.5	±30	±40	±40	%
25- Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.8, 1.5	±30	±40	±40	%
25- Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.2	±35	±50	±50	%
50- Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5	±30	±40	±40	%
50- Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.8, 1.5	±30	±40	±40	%
50- Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.2	±35	±50	±50	%
100- Ω R _D	Internal differential termination (100- Ω setting)	V _{CCIO} = 2.5	±25	±40	±40	%

Figure 1-1: Equation for OCT Variation Without Recalibration

$$R_{OCT} = R_{SCAL} \left(1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

The definitions for the equation are as follows:

- The R_{OCT} value calculated shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- R_{SCAL} is the OCT resistance value at power-up.
- ΔT is the variation of temperature with respect to the temperature at power up.
- ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- dR/dT is the percentage change of R_{SCAL} with temperature.
- dR/dV is the percentage change of R_{SCAL} with voltage.

OCT Variation after Power-Up Calibration

Table 1-10: OCT Variation after Power-Up Calibration for Arria V Devices

This table lists OCT variation with temperature and voltage after power-up calibration. The OCT variation is valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0°C to 85°C .

Symbol	Description	V_{CCIO} (V)	Value	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.100	%/mV
		2.5	0.100	
		1.8	0.100	
		1.5	0.100	
		1.35	0.150	
		1.25	0.150	
		1.2	0.150	

Symbol	V _{OD} Setting ⁽⁵⁸⁾	V _{OD} Value (mV)	V _{OD} Setting ⁽⁵⁸⁾	V _{OD} Value (mV)
	25	500	53	1060
	26	520	54	1080
	27	540	55	1100
	28	560	56	1120
	29	580	57	1140
	30	600	58	1160
	31	620	59	1180
	32	640	60	1200
	33	660		

Transmitter Pre-Emphasis Levels

The following table lists the simulation data on the transmitter pre-emphasis levels in dB for the first post tap under the following conditions:

- Low-frequency data pattern—five 1s and five 0s
- Data rate—2.5 Gbps

The levels listed are a representation of possible pre-emphasis levels under the specified conditions only and the pre-emphasis levels may change with data pattern and data rate.

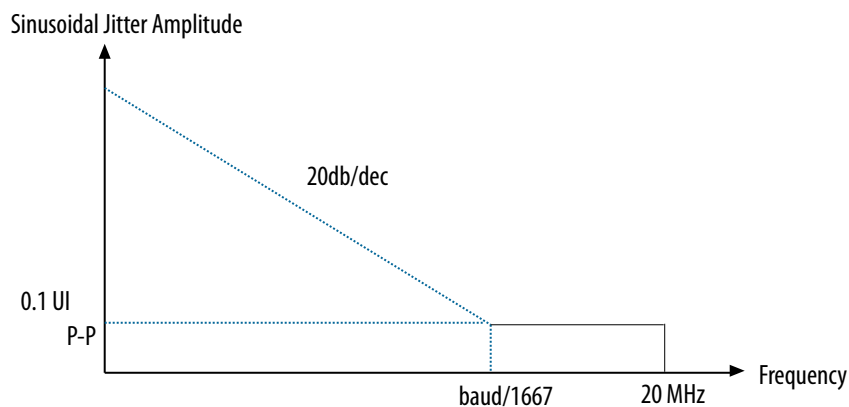
Arria V devices only support 1st post tap pre-emphasis with the following conditions:

- The 1st post tap pre-emphasis settings must satisfy $|B| + |C| \leq 60$ where $|B| = V_{OD}$ setting with termination value, $R_{TERM} = 100 \Omega$ and $|C| = 1st$ post tap pre-emphasis setting.
- $|B| - |C| > 5$ for data rates < 5 Gbps and $|B| - |C| > 8.25$ for data rates > 5 Gbps.
- $(V_{MAX}/V_{MIN} - 1)\% < 600\%$, where $V_{MAX} = |B| + |C|$ and $V_{MIN} = |B| - |C|$.

Exception for PCIe Gen2 design: V_{OD} setting = 43 and pre-emphasis setting = 19 are allowed for PCIe Gen2 design with transmit de-emphasis – 6dB setting (pipe_txdeemp = 1'b0) using Altera PCIe Hard IP and PIPE IP cores.

⁽⁵⁸⁾ Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.

Figure 1-6: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate Less than 1.25 Gbps



DLL Frequency Range Specifications

Table 1-43: DLL Frequency Range Specifications for Arria V Devices

Parameter	-I3, -C4	-I5, -C5	-C6	Unit
DLL operating frequency range	200 – 667	200 – 667	200 – 667	MHz

DQS Logic Block Specifications

Table 1-44: DQS Phase Shift Error Specifications for DLL-Delayed Clock ($t_{\text{DQS_PSERR}}$) for Arria V Devices

This error specification is the absolute maximum and minimum error.

Number of DQS Delay Buffer	-I3, -C4	-I5, -C5	-C6	Unit
2	40	80	80	ps

Symbol	Description	Min	Max	Unit
T_h	SPI MISO hold time	1	—	ns
$T_{\text{duty cycle}}$	SPI_CLK duty cycle	45	55	%
T_{dssfrst}	Output delay SPI_SS valid before first clock edge	8	—	ns
T_{dsslst}	Output delay SPI_SS valid after last clock edge	8	—	ns
T_{dio}	Master-out slave-in (MOSI) output delay	–1	1	ns

⁽⁸⁶⁾ This value is based on $\text{rx_sample_dly} = 1$ and $\text{spi_m_clk} = 120$ MHz. spi_m_clk is the internal clock that is used by SPI Master to derive its SCLK_OUT . These timings are based on rx_sample_dly of 1. This delay can be adjusted as needed to accommodate slower response times from the slave. Note that a delay of 0 is not allowed. The setup time can be used as a reference starting point. It is very crucial to do a calibration to get the correct rx_sample_dly value because each SPI slave device may have different output delay and each application board may have different path delay. For more information about rx_sample_delay , refer to the SPI Controller chapter in the Hard Processor System Technical Reference Manual.

After the Boot ROM code exits and control is passed to the preloader, software can adjust the value of `drvsel` and `smp1sel` via the system manager. `drvsel` can be set from 1 to 7 and `smp1sel` can be set from 0 to 7. While the preloader is executing, the values for `SDMMC_CLK` and `SDMMC_CLK_OUT` increase to a maximum of 200 MHz and 50 MHz respectively.

The SD/MMC interface calibration support will be available in a future release of the preloader through the SoC EDS software update.

Symbol	Description	Min	Max	Unit
$T_{\text{sdmmc_clk}}$ (internal reference clock)	SDMMC_CLK clock period (Identification mode)	20	—	ns
	SDMMC_CLK clock period (Default speed mode)	5	—	ns
	SDMMC_CLK clock period (High speed mode)	5	—	ns
$T_{\text{sdmmc_clk_out}}$ (interface output clock)	SDMMC_CLK_OUT clock period (Identification mode)	2500	—	ns
	SDMMC_CLK_OUT clock period (Default speed mode)	40	—	ns
	SDMMC_CLK_OUT clock period (High speed mode)	20	—	ns
$T_{\text{duty cycle}}$	SDMMC_CLK_OUT duty cycle	45	55	%
T_d	SDMMC_CMD/SDMMC_D output delay	$(T_{\text{sdmmc_clk}} \times \text{drvsel})/2 - 1.23^{(87)}$	$(T_{\text{sdmmc_clk}} \times \text{drvsel})/2 + 1.69^{(87)}$	ns
T_{su}	Input setup time	$1.05 - (T_{\text{sdmmc_clk}} \times \text{smp1sel})/2^{(88)}$	—	ns
T_h	Input hold time	$(T_{\text{sdmmc_clk}} \times \text{smp1sel})/2^{(88)}$	—	ns

⁽⁸⁷⁾ `drvsel` is the drive clock phase shift select value.

⁽⁸⁸⁾ `smp1sel` is the sample clock phase shift select value.

Related Information

- [PS Configuration Timing](#) on page 1-81
- [AS Configuration Timing](#)
Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
DCLK frequency in AS configuration scheme	5.3	7.9	12.5	MHz
	10.6	15.7	25.0	MHz
	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

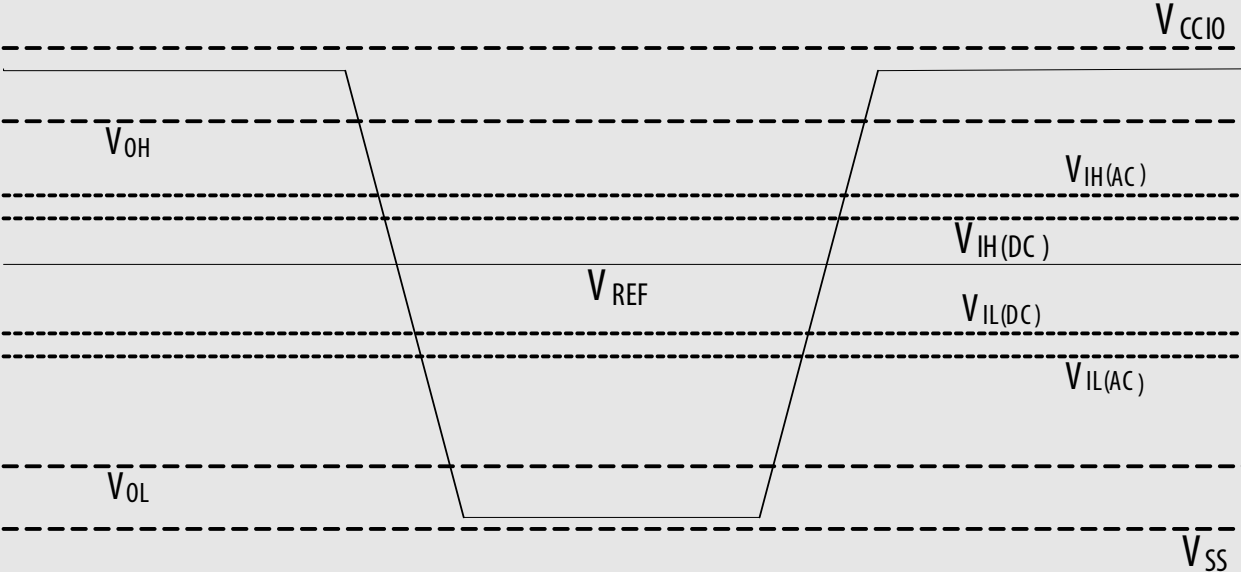
PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽¹⁰³⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽¹⁰⁴⁾	μs

⁽¹⁰³⁾ You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽¹⁰⁴⁾ You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

Term	Definition
Single-ended voltage referenced I/O standard	<p>The JEDEC standard for the SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing.</p> <p>Single-Ended Voltage Referenced I/O Standard</p> 
t_C	High-speed receiver/transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on high-speed transmitter output clock.

Date	Version	Changes
June 2015	2015.06.16	<ul style="list-style-type: none"> Added the supported data rates for the following output standards using true LVDS output buffer types in the High-Speed I/O Specifications for Arria V Devices table: <ul style="list-style-type: none"> True RSDS output standard: data rates of up to 360 Mbps True mini-LVDS output standard: data rates of up to 400 Mbps Added note in the condition for Transmitter—Emulated Differential I/O Standards f_{HSDR} data rate parameter in the High-Speed I/O Specifications for Arria V Devices table. Note: When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported. Changed Queued Serial Peripheral Interface (QSPI) to Quad Serial Peripheral Interface (SPI) Flash. Updated T_h location in I²C Timing Diagram. Updated T_{wp} location in NAND Address Latch Timing Diagram. Corrected the unit for t_{DH} from ns to s in FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices table. Updated the maximum value for t_{CO} from 4 ns to 2 ns in AS Timing Parameters for AS $\times 1$ and $\times 4$ Configurations in Arria V Devices table. Moved the following timing diagrams to the Configuration, Design Security, and Remote System Upgrades in Arria V Devices chapter. <ul style="list-style-type: none"> FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is 1 FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is >1 AS Configuration Timing Waveform PS Configuration Timing Waveform

Symbol	Description	Minimum ⁽¹¹⁸⁾	Typical	Maximum ⁽¹¹⁸⁾	Unit
$V_{CCR_GXBL}^{(121)}$	Receiver analog power supply (left side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
$V_{CCR_GXBR}^{(121)}$	Receiver analog power supply (right side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
$V_{CCT_GXBL}^{(121)}$	Transmitter analog power supply (left side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
$V_{CCT_GXBR}^{(121)}$	Transmitter analog power supply (right side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	1.425	1.5	1.575	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	1.425	1.5	1.575	V

⁽¹¹⁸⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹²¹⁾ This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rate up to 6.5 Gbps, you can connect this supply to 0.85 V.

Transceiver Power Supply Requirements

Table 2-7: Transceiver Power Supply Voltage Requirements for Arria V GZ Devices

Conditions	VCCR_GXB and VCCT_GXB ⁽¹²²⁾	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true: <ul style="list-style-type: none"> Data rate > 10.3 Gbps. DFE is used. 	1.05	3.0	1.5	V
If ANY of the following conditions are true ⁽¹²³⁾ : <ul style="list-style-type: none"> ATX PLL is used. Data rate > 6.5Gbps. DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used. 	1.0			
If ALL of the following conditions are true: <ul style="list-style-type: none"> ATX PLL is not used. Data rate ≤ 6.5Gbps. DFE, AEQ, and EyeQ are not used. 	0.85	2.5		

DC Characteristics

Supply Current

Standby current is the current drawn from the respective power rails used for power budgeting.

Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

⁽¹²²⁾ If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to 0.85 V, they can be shared with the VCC core supply.

⁽¹²³⁾ Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

Symbol	Description	Conditions	Calibration Accuracy		Unit
			C3, I3L	C4, I4	
25-Ω R _S	Internal series termination with calibration (25-Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
50-Ω R _S	Internal series termination with calibration (50-Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
34-Ω and 40-Ω R _S	Internal series termination with calibration (34-Ω and 40-Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R _S	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V _{CCIO} = 1.2 V	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R _T	Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R _T	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	%
25-Ω R _{S_left_shift}	Internal left shift series termination with calibration (25-Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%

Table 2-11: OCT Without Calibration Resistance Tolerance Specifications for Arria V GZ Devices

Symbol	Description	Conditions	Resistance Tolerance		Unit
			C3, I3L	C4, I4	
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 3.0 and 2.5 V	±40	±40	%

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-12 Class I, II	1.14	1.20	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	—	—	—

Table 2-18: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V GZ Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{ol} (mA)	I_{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{ol} (mA)$	$I_{oh} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
SSTL-135 Class I, II	—	$V_{REF} - 0.09$	$V_{REF} + 0.09$	—	$V_{REF} - 0.16$	$V_{REF} + 0.16$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-125 Class I, II	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-12 Class I, II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	—	—

Symbol	Parameter	Min	Typ	Max	Unit
$t_{\text{OUTPJ_IO}}^{(173), (175)}$	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{FOUTPJ_IO}}^{(173), (175), (176)}$	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{OUTCCJ_IO}}^{(173), (175)}$	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{FOUTCCJ_IO}}^{(173), (175), (176)}$	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC_OUTPJ_DC}}^{(173), (177)}$	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
dK_{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits

⁽¹⁷⁵⁾ The external memory interface clock output jitter specifications use a different measurement method, which is available in the "Memory Output Clock Jitter Specification for Arria V GZ Devices" table.

⁽¹⁷⁶⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be ≥ 1000 MHz.

⁽¹⁷⁷⁾ The cascaded PLL specification is only applicable with the following condition:

- Upstream PLL: $0.59\text{MHz} \leq \text{Upstream PLL BW} < 1$ MHz
- Downstream PLL: $\text{Downstream PLL BW} > 2$ MHz

Related Information

Configuration, Design Security, and Remote System Upgrades in Arria V Devices

Initialization

Table 2-61: Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices

Initialization Clock Source	Configuration Schemes	Maximum Frequency (MHz)	Minimum Number of Clock Cycles
Internal Oscillator	AS, PS, FPP	12.5	8576
CLKUSR ⁽²²²⁾	PS, FPP	125	
	AS	100	
DCLK	PS, FPP	125	

Configuration Files

Use the following table to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal file (.hex) or tabular text file (.tcf) format, have different file sizes.

For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size.

⁽²²¹⁾ To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

⁽²²²⁾ To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

Related Information

- [Configuration, Design Security, and Remote System Upgrades in Arria V Devices](#)
For more information about the reconfiguration input for the ALTREMOTE_UPDATE IP core, refer to the “User Watchdog Timer” section.
- [Configuration, Design Security, and Remote System Upgrades in Arria V Devices](#)
For more information about the reset_timer input for the ALTREMOTE_UPDATE IP core, refer to the “Remote System Upgrade State Machine” section.

User Watchdog Internal Oscillator Frequency Specification

Table 2-65: User Watchdog Internal Oscillator Frequency Specifications

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis.

The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

Related Information

[Arria V Devices Documentation page](#)

For the Excel-based I/O Timing spreadsheet

⁽²²⁶⁾ This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification. For more information, refer to the “Remote System Upgrade State Machine” section in the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

⁽²²⁷⁾ This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification. For more information, refer to the “User Watchdog Timer” section in the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

Term	Definition
t_C	High-speed receiver and transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock.
t_{FALL}	Signal high-to-low transition time (80-20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
t_{RISE}	Signal low-to-high transition time (20-80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. ($TUI = 1/(\text{receiver input clock frequency multiplication factor}) = t_C/w$)
$V_{CM(DC)}$	DC common mode input voltage.
V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{IH(AC)}$	High-level AC input voltage
$V_{IH(DC)}$	High-level DC input voltage
V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{IL(AC)}$	Low-level AC input voltage
$V_{IL(DC)}$	Low-level DC input voltage